



规格书

SPECIFICATION

CUSTOMER NAME	客户名称:	
CUSTOMER NO.	客户编号:	
SERIES	系 列:	线对板连接器间距3.0mm
MODEL NO.	型 号:	XB-X30-PCB series
DRAWING NO.	图 形 号:	Line to board connector spacing 3.0mm

If specification of this product meets your request, please confirm all the items of it and return to us with signature and stamp, it will be basis of our production and record. Thanks your cooperation in advance!

若此产品规格符合贵司要求，敬请确认此规格书内所有项目
并签名和盖章后回传给我司，以作我司产品制作之
依据和存档之用，多谢合作！

EXAMINE & APPROVAL 审批

APPROVE 接受	NOT APPROVE 不接受
SIGNATURE 签署 STAMP 盖章 DATE 日期	

PREPARED BY.制表人	CHECKED BY.校对	APPROVED BY.审核	APPROVAL BY.批准
研发部 戴海明 2022. 06. 08	品质部 黄自清 2022. 06. 08	工程部 庞军 2022. 06. 08	总经办 吴量 2022. 06. 08

东莞市溪榜电子有限公司

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Quality core! Afterburner for Made in China!

 XB Connector	Doc. No.	XB-X30-PCB	Page No.	1/9
	Date Issued	2024-6-8	Prepared by	He.Long.Fei
	Date revised	2024-6-8	checked by	Long.Liu.Ting
Product Specification	Rev. No.	01	Approved by	Lai.Hai.Jie
Title : 3.0mm Pitch XB-X30-PCB Series Connector				

1. SCOPE(适用范围)

This specification covers the performance, tests and quality requirements for the 3.0mm series wire to board connector. (XB Connector)
本规范涵盖了盖 3.0mm 系列线对板连接器性能、测试和质量要求)

2. PRODUCT DESCRIPTION(产品描述)

DESCRIPTION(描述)	Part Number(料号)
Terminal 端子	XB-X30-PCB-108D
Housing 胶壳	XB-X30-PCB-108M
Wafer 针座 线对板连接器间距2.54mm	XB-X30-PCB-108

3. APPLICABLE DOCUMENT (适用文件)

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence. (XB Connectivity 下列文件构成本规范的一部分，在此规定的范围内。本规范要求与产品图纸有冲突时，以产品图纸为准。如果本规范的要求与参考文件发生冲突，应以本规范为准。)

4. REQUIREMENTS (要求)

4.1. Design and Structure (设计和结构)

Product shall be of the design, structure and physical dimensions specified on the applicable product drawing. (XB Connectivity 产品的设计、结构和物理尺寸参考所适用的产品图纸)

4.2. Materials/ Finish (材料/表面处理)

Specification 规格内容	Materials 材质	Disposal of Surface 表面处理
Terminal 端子	Phosphor Bronze 磷铜	Tin Plated: Over 70μ. Nickel: Over 30μ”

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Housing胶壳		PA66	UL 94V-2/UL94V-0
Wafe 针座	Base	PA9T / PA66	UL 94V-2/UL94V-0
	PIN	Brass 黄铜	Over Tin 70μ" Plated ; Over 30μ" Nickel

Please Refer to the Project drawing for the above Specification. (上述参数请以工程图为准)

4.3. Ratings (额定功率)

XB Connectivity Item(项目)	Standard(标准)	
Rated Voltage (Maximum) 额定电压	125V 250V	AC/DC
Rated Current (Maximum) 额定电流	5A	
Ambient temperature Range 使用温度范围	-25℃ ~+85℃ From -25 to +85 degree centigrade	
Applicable wire insulation O.D 适用线径	AWG 28#~32# Insulation O.D. 1.00mm(Max.)	
NOTE备注 : Including terminal temperature rise 升温时含端子		

5. TEST STANDARD (测试条件)

5.1 Unless otherwise specified, the standard range of atmospheric conditions for making measurements and tests are as follows (除另有说明外, 用以进行测量和测试的标准环境条件范围如下)

Ambient temperature(环境温度): 5℃ to 35℃

Normal humidity (正常湿度): 45% to 85%

Air pressure (气压): 86Kpa to 106Kpa

5.2 However if doubt arises on the decision based on the measured Values under the above-mentioned Conditions.The following conditions shall be employed:
(但是在对判定产生疑问时,按下述状态实施)

Temperature (温度): 20±2℃

Relative humidity (相对湿度): 65±5%

Air pressure (气压): 86Kpa to 106Kpa

8. PERFORMANCE AND TEST DESCRIPTION (性能和测试类型)

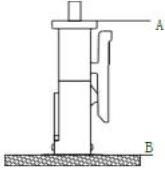
8.1 APPEARANCE (外观)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
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1	Appearance (外观)	Visual. (目视)	Should not have any flaw Scratch discoloration and crushed (无任何裂痕、刮伤、污染和变形)
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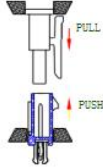
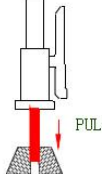
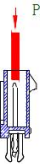
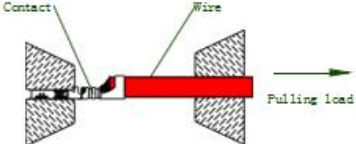
8.2 ELECTRICAL (电气)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	contact resistance (接触阻抗)	Based upon EIA-364-06A. Mate connectors, measure by dry circuit, 20mV MAX, 10mA. (公母配合, 开放电压 20mV 以下, 电流 10mA 检测连接器 A~B 区) 	Initial (初始) : 10 milliohms Max. After Test (测试后) : 20 milliohms Max.
2	Insulation Resistance (绝缘阻抗)	Based upon EIA-364-21B/MIL-STD-202 Method 302 Cond. B Mate connectors, apply 500V DC between adjacent terminal or ground. (公母配合, 在相邻端子, 端子与地片之间, 使用500V 的直流电, 检测连接器)	1000 MΩ min.
3	Dielectric strength (耐电压)	Based upon EIA-364-20A/MIL-STD-202 Method 301 Mate connectors, apply 1000V AC for 1 minute between adjacent terminal or ground. (公母配合, 在相邻端子, 端子与地片之间, 使用1000V 的交流电 1 分钟, 检测连接器)	There shall be no breakdown. (无击穿、闪烁现象)
4	Contact resistance on crimped portion (铆线后端子接触阻抗)	Crimp the applicable wire on to the terminal measure by dry circuit 20mV MAX, 10mA. (铆线后之端子, 开放电压 20mV 以下, 电流 10mA检测连接器)	10 milliohms

8.3 MECHANICAL (机械)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
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1	Insertion & Retention Force (插拔力)	Insert and withdraw Connectors at the speed rate of 25.4±3mm/minute. (以每分钟 25.4±3mm 的速率插入和拔出) 	Refer to paragraph 6 参照第 10 项			
2	Terminal/ Housing Retention Force (端子保持力)	Apply axial pull out force at the speed rate of 25.4±3mm/minute on the terminal assembled in the housing. (以每分 25.4±3mm 的速率, 将端子从 Housing 内轴向拔出的力量。) 	24.5N {2.5kgf}Min.			
3	Terminal Insertion Force (端子插入力)	Insert the crimped terminal into the housing. (铆线后之端子插入Housing 所需最大力量)	14.7N {1.5kgf} Max.			
4	PIN Retention Force (PIN针保持力)	Apply axial push force at the speed rate of 25.4±3mm/minute. (以每分 25.4±3mm 的速率, 将 PIN 针从Wafer 内轴向拔出的力量) 	13.7N {1.4kgf} min.			
5	Tensile strength (Crimped connections) (端子压着强度)	Fix the crimped terminal, apply axial pull out force on the wire. (Do not crimp insulation part). (固定铆线后的端子, 使电线与端子分离时所需的最小力量) 	AWG	#20	#22	#24
			Spec. kgf. Min.	6.0	4.0	2.0
			Note> As for unspecified wire sizes in this specification define values with clients			
6	Repeated Insertion/ Withdrawal (重复插拔)	When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute. (以每分钟不超过 10 次的速率, 将公母插拔30 次。)	Contact Resistance (接触阻抗) : 20 milliohms Max.			

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7	Vibration (耐振动性)	Based upon EIA-364-28B/MIL-STD-202 Method 213B Cond.A Amplitude (振幅) : 1.5mm P-P Sweep time (频率) : 10~55~10 HZ in 1 minute Duration (持续时间) : 2 hours in each X.Y.Z axials. (每轴向 2 小时)	Appearance外观: No Damage无异状 Contact Resistance接触阻抗: 20 milliohms Max. Discontinuity瞬断: 1 micro- second Max.
8	Shock (耐冲击性)	Based upon EIA-364-27B/MIL-STD-202 Method 213B Cond.A Pulse width (冲击时间) : 11 msec., Waveform (波形) : half sine, 490m/s{50G}, 3 strokes in each X.Y.Z. axes. (加速度最大50G, 沿3个互相垂直达的方向)	Appearance外观: No Damage无异状 Contact Resistance接触阻抗: 20 milliohms Max. Discontinuity瞬断: 1 micro- second Max.

8.4 ENVIRONMENTAL (环境)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	Temperature Rise (温升测试)	Carrying rated current load. (UL 1977) (公母对插后, 在通过额定电流下, 所测定的温度)	30℃ Max.
2	Heat Resistance (耐热性)	Based upon MIL-STD-202 Method 108A Cond.A 85±2℃, 96 hours.	Appearance外观: No Damage无异状 Contact Resistance接触阻抗: 20 milliohms Max.
3	Cold Resistance (耐寒性)	Based upon EIA-364-105 -25±5℃, 96 hours.	Appearance外观: No Damage无异状 Contact Resistance接触阻抗: 20 milliohms Max.

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4	Humidity (耐湿性)	Based upon EIA-364-31A/MIL-STD-202 Method 103B Cond.B Temperature (温度) : 40±2℃ Relative Humidity (湿度) : 90~95% Duration (持续时间) : 96 hours	Appearance外观: No Damage无异状 Contact Resistance接触阻抗: 20 milliohms Max. Insulation Resistance绝缘阻抗: 1000 MΩ min.
5	Temperature Cycling (温度变化)	Based upon EIA-364-32B 5 cycles of: a) -55℃ 30 minutes. b) +85℃ 30 minutes. (从-55℃持续 30 分锺升至+85℃持续 30 分锺, 循环 5 次)	Appearance外观: No Damage无异状 Contact Resistance接触阻抗: 20 milliohms Max.
6	Salt Spray (盐水喷雾)	Based upon EIA-364-26A/MIL-STD-202 Method 101D Cond.B 24±1 hours exposure to a salt spray from the 5±1% solution at 35±2℃. (在温度 35±2℃, 盐水浓度 5±1%下, 盐水喷雾24±1 小时) 注: 此项测试只针对先冲后镀端	Appearance外观: No Damage无异状 Contact Resistance接触阻抗: 20 milliohms Max.
7	Solder-ability (焊锡附着性)	Based upon EIA-364-52 Soldering Time焊接时间: 3±0.5second. Solder Temperature焊接温度: 245±5℃.	Immersed area must show no voids, pin holes. 浸渍面积需95%以上
8	Solder- Resistance (焊锡耐热性)	Based upon EIA-364-56A Soldering time焊接时间: 3~5 sec Solder Temperature焊接温度: 250±5℃.	Appearance外观: No Damage无异状

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9. PACKAGING 包装

Please refer to the packing drawing. 请参考产品包装图纸
参考附件

10. INSERTION/WITHDRAWAL FORCE 综合插入力及拔出力:

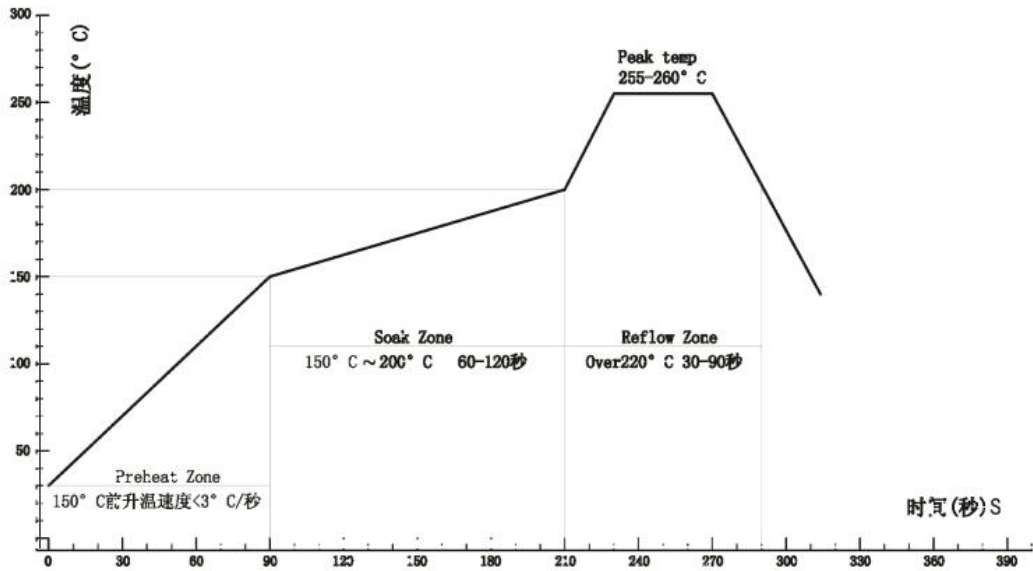
参考附件

11. SOLDERING 焊接:

- 11.1. Wave soldering (波峰焊) : DIP Suggestions solder temperature at 260°C(500°F)
max.5 seconds . DIP型推荐焊接焊锡温度为260°C (500 °F) 最多5秒
- 11.2. Hand soldering (手焊) : Use a soldering iron of 30 watts controlled at 350°C
approximately 5 seconds. while applying solder.
使用30W烙铁控制温度在350°C,焊接时长约5秒

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11.3. Reflow soldering profile (回炉焊) :When the maximum temperature of the reflow furnace is 260 °C and the temperature is 260 °c. 10 seconds MAX. (reference) SMT型回焊炉最高温度为260℃，温度为260℃时，最长时间不超过10秒（如图）



Rev.	Description	Date revised	Created/ Revised by
01	New Release	2024-6-8	He.Long.Fei